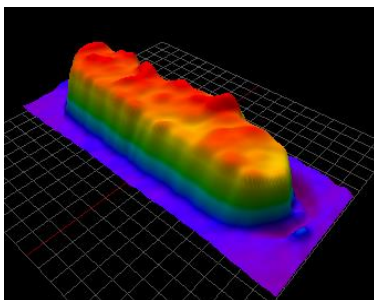
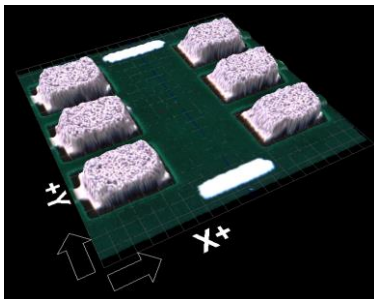


MS-11 3D SPI Series

- ▶ Exclusive 15MP CoaXPress Camera System
- ▶ Dual Projection Shadow Free Moiré Technology
- ▶ Precision Compound Telecentric Camera Lens
- ▶ Automated Z-Height Calibration System
- ▶ Automated PCB Under Board Support System
- ▶ Precision PCB Warpage Compensation
- ▶ Closed Loop Communication With Screen Printer
- ▶ Absolute Repeatability and Reproducibility
- ▶ INTELLISYS® Industry 4.0 Intelligent Factory Automation System



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AWARDS
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SMT/PCB PACKAGING

MS-11 3D SPI Series Specifications

Standard Features:

- ▶ Intel® Multi-Core PC, 32" Flat Screen LCD Monitor, Windows 10™ OS, HDD, Mouse & Keyboard, Network LAN Card.
- ▶ Three (3) Stage High-Speed Conveyor System with Programmable Width Control and Automatic PCB Support.
- ▶ Advanced High-Intensity RGB LED Lighting System.
- ▶ ePM-SPI Gerber Programming Software (One Seat Included with Purchase).
- ▶ Auto-Focus Moveable Z-Axis System with Automatic PCB Warpage Compensation.
- ▶ KTL - Calibration Target Fixture.
- ▶ Statistical Process Control (SPC) Software (Local System Software).

Options:

- ▶ 15MP CoaXPress Top-Down Camera System (See Specifications).
- ▶ ePM-SPI CAD Import Software. ODB++ Import Module Sold Separately (Requires ePM SPI).
- ▶ 2D Bar Code Reader Options: Gun Type, Camera Type and External Mount.
- ▶ Remote PC - Software Purchased Separately.
- ▶ Remote Software: Statistical Process Control (SPC) Software,
- ▶ Total Remote Management Software (TRMS) - Requires Server Software for Remote PC and Client Software on All Machines.
- ▶ INTELLI-TRACK® Process Control Software - Requires Server Software for Remote PC and Client Software on All Machines.
- ▶ SVN Multi-System Version Control Software - Requires Separate PC Server.

System Specifications:

(Subject to change without prior notice)

PCB Inspection Area	
MS-11U	60 mm x 60 mm to 660 mm x 610 mm (2.36" x 2.36" to 26.0" x 24.1") PCB Indexing Mode: 60 mm x 60 mm to 1,320 mm x 610 mm (2.36" x 2.36" to 51.97" x 24.1")

Vision System (FOV Size)			
15MP CoaXPress: (3,904 x 3,904 @ 120 fps)	Option 1	Pixel Resolution: 15 um	58.56 mm x 58.56 mm (2.31" x 2.31")
	Option 2	Pixel Resolution: 10 um	39.04 mm x 39.04 mm (1.54" x 1.54")

Inspection Technology	
3D Inspection Technology	Dual Projection Shadow Free Moiré Phase Step Image Processing
2D Inspection Technology	15MP CoaXPress Camera System
Height Resolution	±1 um
Height Accuracy on Calibration Fixture	± 1%
Repeatability on Calibration Fixture	Height: ± 1% / Volume: ± 2%
Inspection Height	Maximum: 500 um / Minimum: 40um
3D Inspection Item	Solder Deposition: Height, Volume / Area, Solder Bridge, X/Y Offset, Shape Deformity, etc.

Additional Specifications	
Lens Configuration	Precision Telecentric Compound Lens Design
Lighting System	Advanced High-Intensity RGB LED Lighting System.
PCB Surface Clearance	Top-Side Clearance: 20 mm / Bottom-Side Clearance: 50 mm
PCB Edge Clearance	Top-Edge Clearance: 3 mm / Bottom-Edge Clearance: 3.5 mm
Maximum PCB Warpage	±2 mm
Maximum PCB Weight	Standard: 4 Kg (8.82 Lbs.)
PCB Thickness Range	Standard: 0.5 mm - 5 mm
Robot Positioning System	Precision Closed Loop AC Servo Drive, Resolution: 1 um / Repeatability: ±10 um
Power Requirements	Single Phase 200~240V 50~60Hz; 1.1 KW, Breaker Capacity: 25 Amp
Air Requirements	5 Kgf / cm ² (0.5 Mpa); (71 PSI)

Machine Dimensions and Weight		
MS-11U	1,270 mm W x 1,680 mm D x 1,500 mm H (50" x 66.14" x 59")	1,200 Kg (2,645 lbs.)